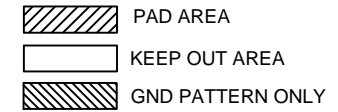


RECOMMENDED PCB LAYOUT
 GENERAY TOLERANCE ±0.05
 XKB Connectivity

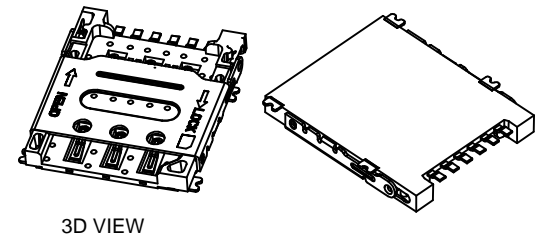


XKB Connectivity
 NOTE:

- 1.材料 Material:
 - 1-1 胶壳 Housing:High Temperature Thermoplastic.
(LCP S475jColor Black UL94V-0
 - 1-2 触点 Contact:Phosphor Branze(C5210R-HT=0.15 ±0.02mm)
 - 1-3 盖 Cover:SUS301-HT=0.20 ±0.03mm
- 2.电镀 Plating:
 - 接触端子 Contact terminal:
 - 接触电阻 Contact area: Gold 1u" Min.
 - 焊料区 Solder area: Gold 0.8u" Min
 - 底镀 Underplating: Ni overall 50U"Min,
- 3.规格 Specification:
 - 3-1.接触电阻 CONTACT RESISTANCE:50 Milliohms Max
 - 3-2.绝缘电阻 INSULATION RESISTANCE:1.000 Megohms Min.
 - 3-3.绝缘耐压 DIELECTRIC WITHSTANDING VOLTAGE:500V AC FOR 1MINUTE.
 - 3-4.工作温度范围 OPERATION TEMPERATURE RANGE:-25C~+700
 - 3-5.耐用性 DURABILITY:3000 CYCLES
- 4.Product Compliant to RoHs Directive 2002/95/EC and ELV 2000/53/EC
- 5.Part Must Comply Taisol HFWD-3-1-091 Specification.
- 6.Recommending A Metal More Than 0.15mm Thick.
 Please Confirm Solderadility,If Use A Metal Mask Less Than 0.15mm Thick.

NANO SIM CARD
 XKB Connectivity

SIM CARD	
PIN No.	NAME
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O



3D VIEW

					ANGLAR	±5°	DSND		DATE	SCALE: N/A	MODEL TYPE: SIM CARD CONN		
ΔX					L ≤ 4	±0.2	DWN		DATE	VIEW:	PART NO.:		
ΔX					4 < L ≤ 16	±0.3	CHKD		DATE	UNIT: mm/in	DWG NO.:		
ΔX					16 < L ≤ 63	±0.4	APPD		DATE	SIZE: A4	XKNANO-1150		
MARK	DESCRIPTION	DATE	REVISED	APPROVED	L > 63	±0.5					WEIGHT	SHEET	REVISION
	REVISIONS					UNSPECIFIED TOLERANCES		XKB INDUSTRIAL PRECISION CO.,LIMITED			1.0g	1/1	A0
www.xk-dg.cn www.helloxkb.com www.helloxkb.cn													